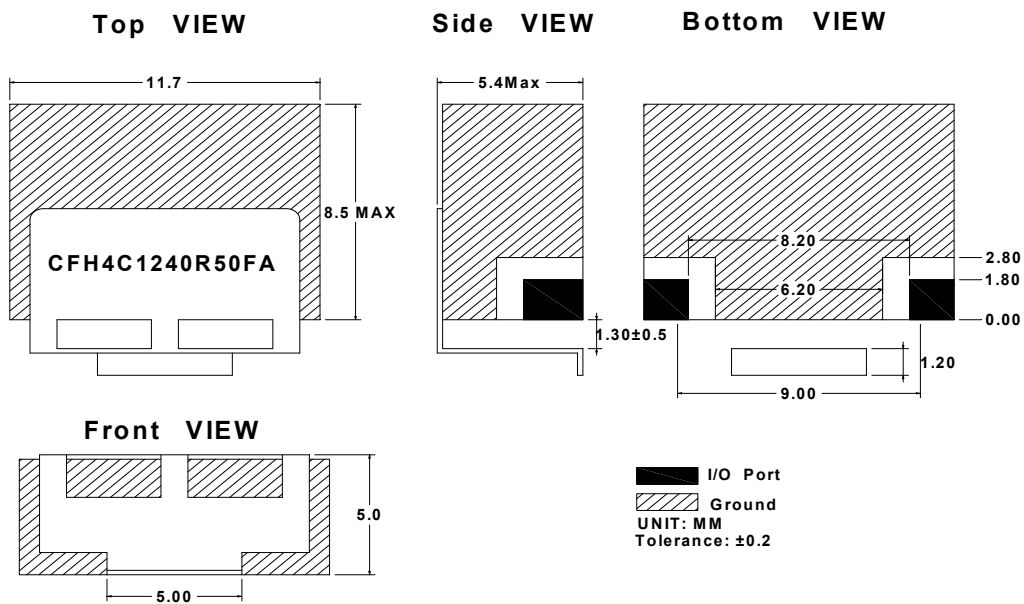


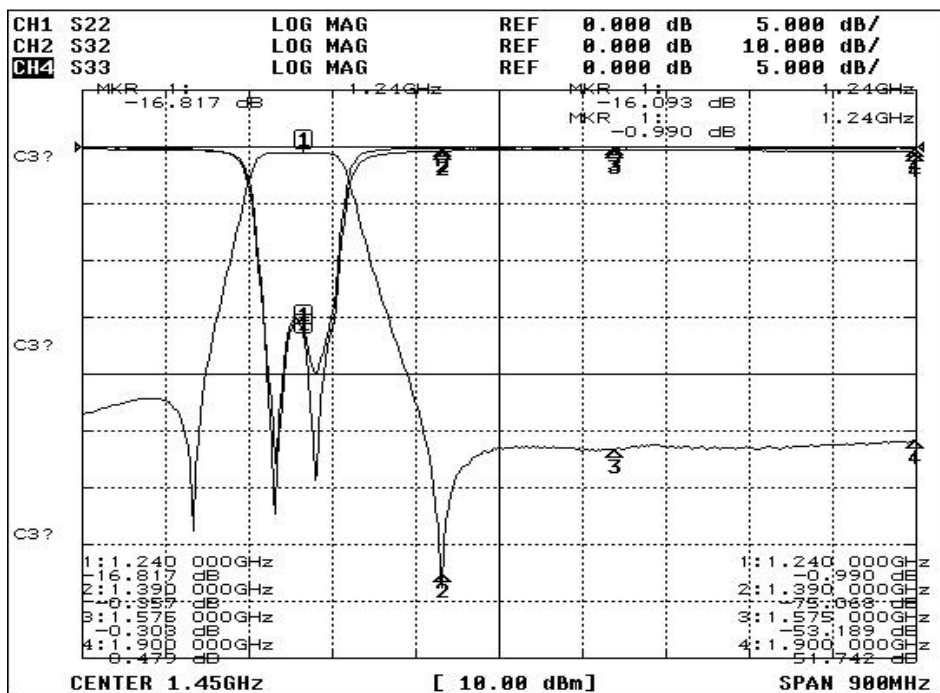
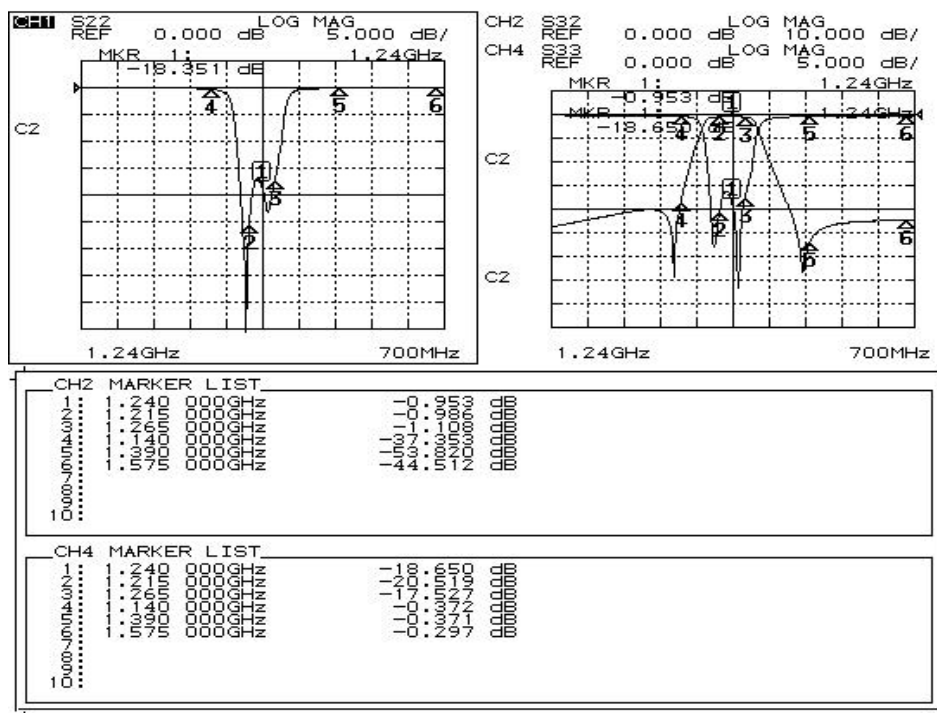
Electrical Specification

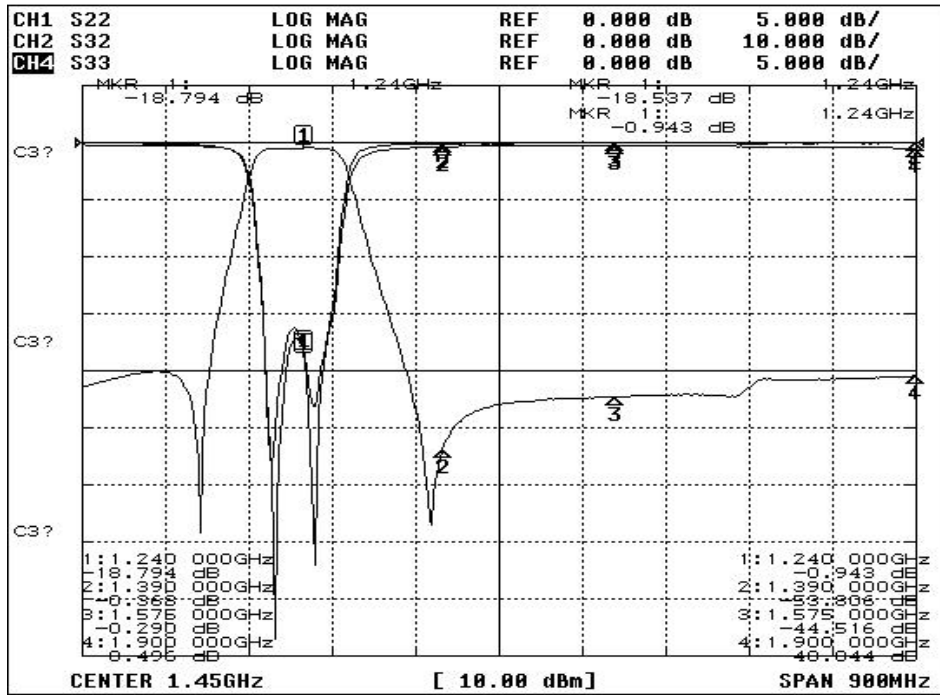
ITEMS	SPEC	UNIT
Center Frequency [fo]	1240.0	MHz
Bandwidth [BW]	$f_o \pm 25.0$ [1215.0 ~ 1265.0]	MHz
Insertion Loss in BW	2.0	dB max
Ripple in BW	0.5 @ $f_o \pm 13.0$	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40.0 dB min @ $f_o \pm 100.0$ [1140.0 ~]	MHz
	48.0 dB min @ $f_o \pm 150.0$ [1390.0 ~]	MHz
	50.0 dB min @ $f_o \pm$ [1575.0 ~]	MHz
	50.0 dB min @ $f_o \pm$ [1900.0 ~]	MHz
Group Delay Variation		ns max
Input Power	1.0	W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

Mechanical Specification



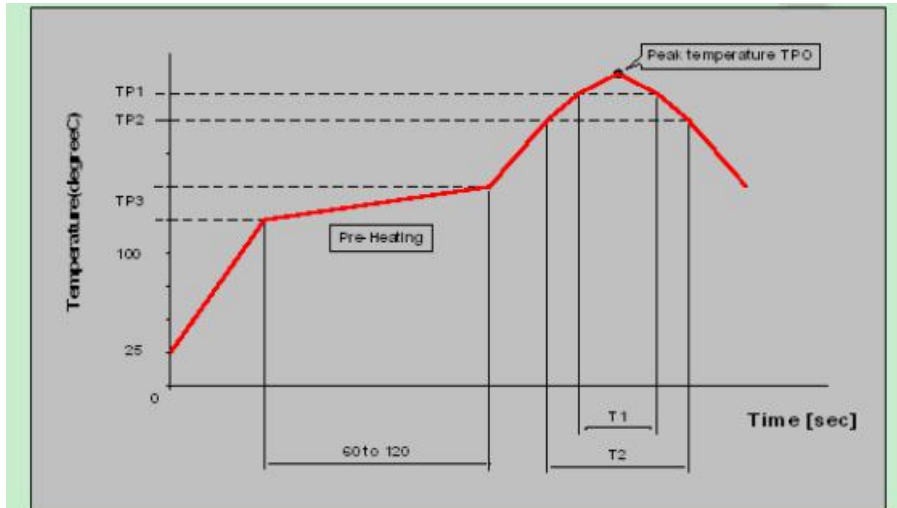
Plot Data





Recommended PC Board Pattern

 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-8	240	20	220	70	150 to 180